



**Electronics Manufacturing Break-out
Session – Closed Loop
Manufacturing**

Presenters



Frank Bleisteiner

Siemens DI FA MF

Senior Director Production Engineering

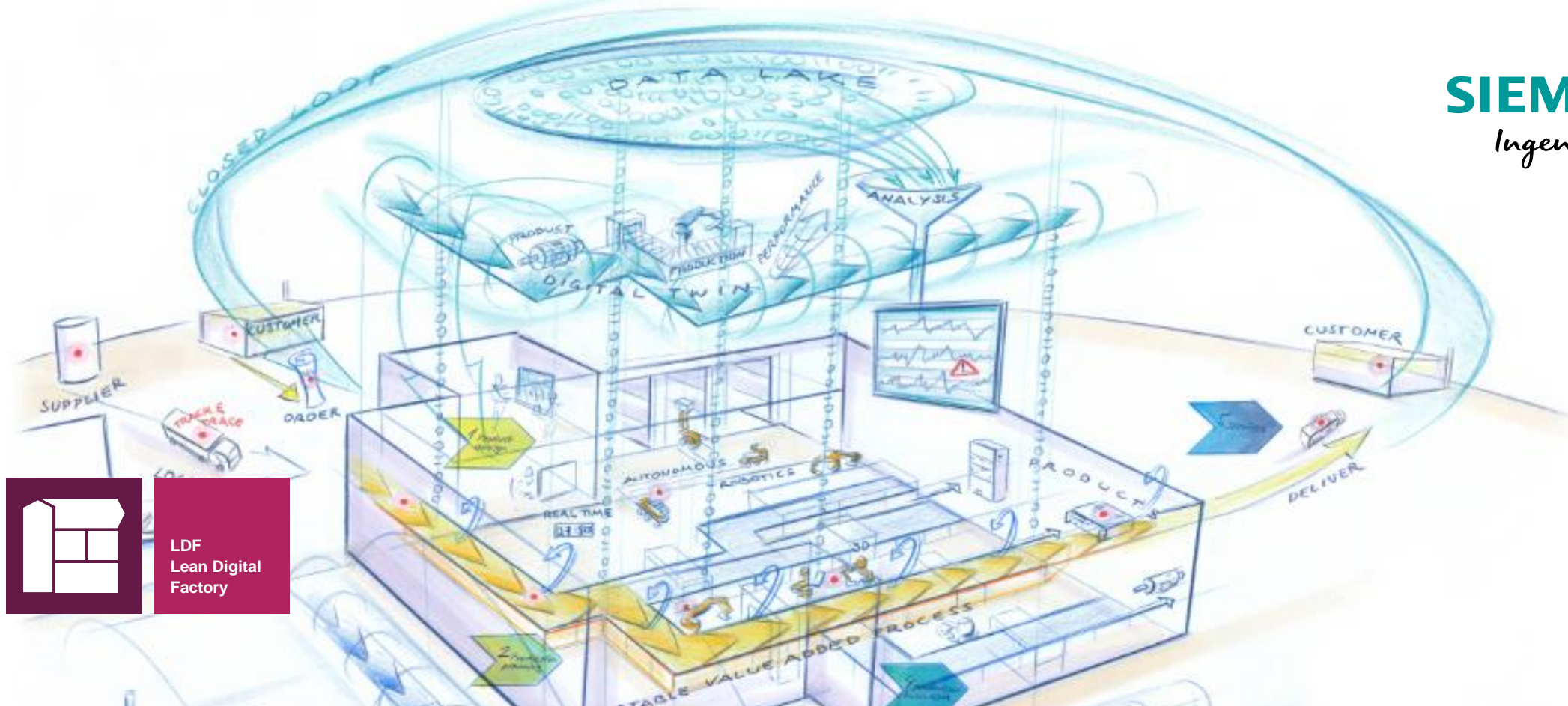


Sagi Reuven

Mentor – Siemens DISW

Business Development

Valor | MOM | Electronics

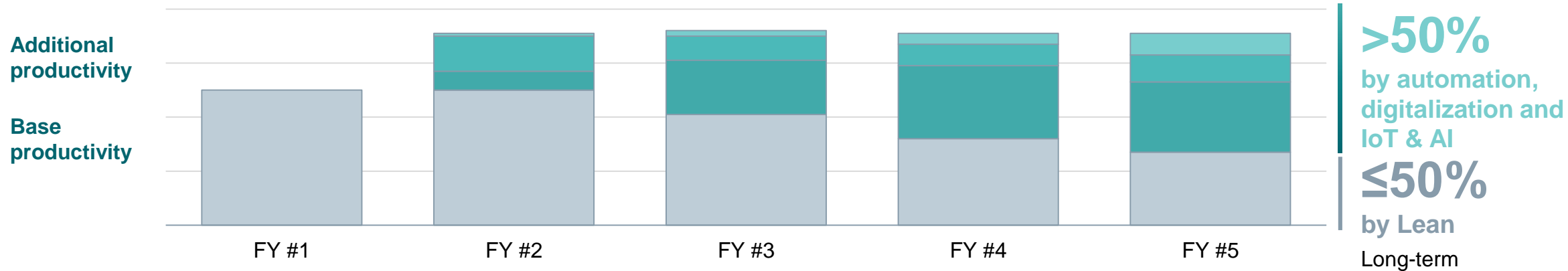
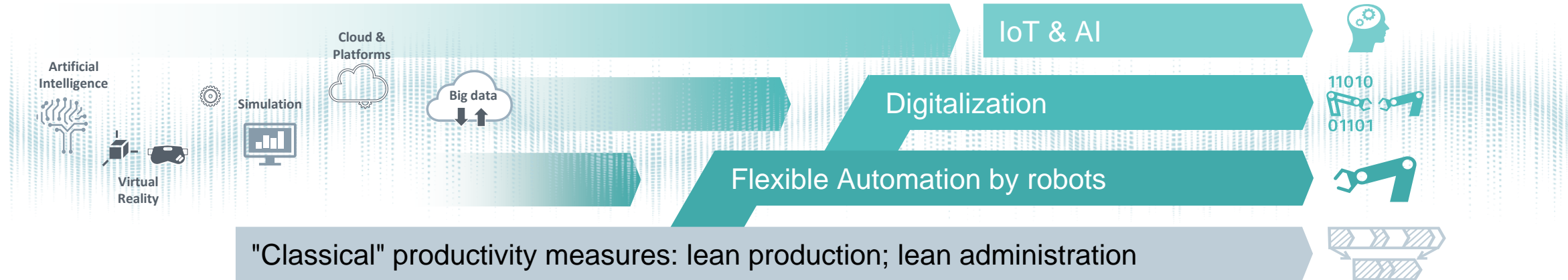


LDF
Lean Digital
Factory

Lean Digital Roadmap of DI

Frank Bleisteiner – Senior Director Production Engineering – DI FA MF

Siemens DI factories strengthen the focus on automation & digitalization hand in hand with lean productivity



LDF guides the way to Digital Transformation

Pilots should be fresh topics using new technology, which are easily scalable and bring measurable value to the organization

Digitalization pilot criteria, working principles



What?

Digitalization pilot criteria

0110110
1011101
0011011
0101010
1100101

New Technology

Introduce / leverages a **new interesting technology** / solution



"Make things easy"

Makes a process / job **more convenient** for employees



Clear benefits

Value-add clear and easy to understand



Competences

Implementable with **available resources** / know how



Timely

Creates **impact within 3-6 months** (1st wave pilots)



Fresh topic

No **negative connotation** from previous experiences



Scalability

Scalable to **larger parts of organization** after small scale pilot

How?

Principles of set-up



Dedicated Teams

Lean dedicated teams **working** on the project



Design thinking

Agile, building up ideas, user-centric, learn & iterate

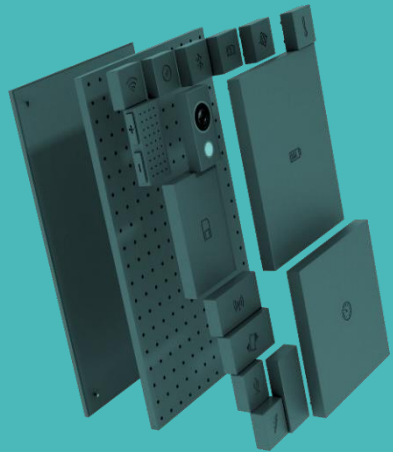
Industry 4.0 - How we Transform a Buzz-word into Manufacturing Excellence in Electronics

“More than 50% of companies that attempt to move to a digital model will fail.”

Source: John Chambers, McKinsey & Company Report
March 2016

Trends and challenges driving MES implementation in Electronics industry

DELIVERING LOT SIZE ONE



↓ Product Lifecycle

↑ Number of NPIs

OPTIMIZING MATERIAL USAGE

COST OF SELECTED PARTS	
Display	\$45
Memory	15
Communications	37.50
Cameras	11
Processor	20
Mechanical	30
Other	37.60
TOTAL PARTS	\$196.10
Labor	4
TOTAL	\$200.10



↑ Lead Time & Cost

↑ Number of Variants

PERSONLIZED PRODUCTS



↓ Time to Market

↑ Agility

COMPLIANCE

ISO/TS 16949

IATF 16949

Medical

↑ Customer Requirements

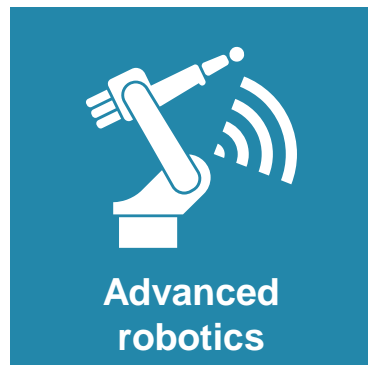
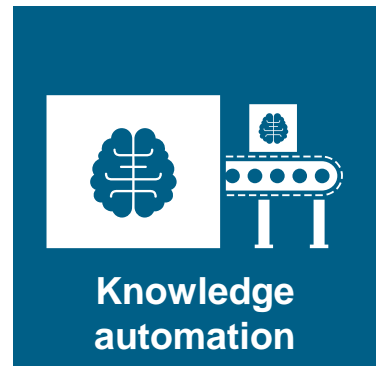
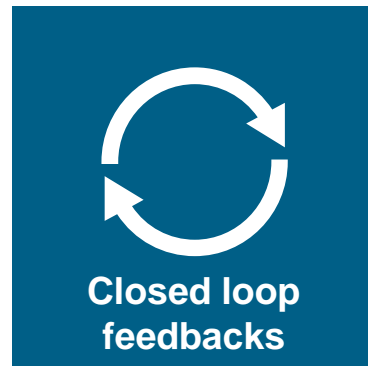
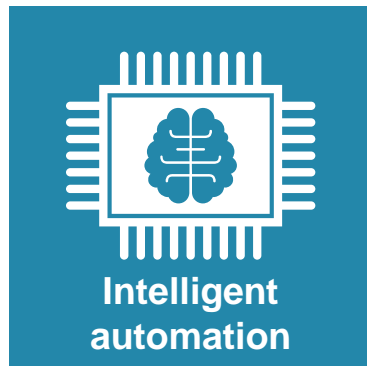
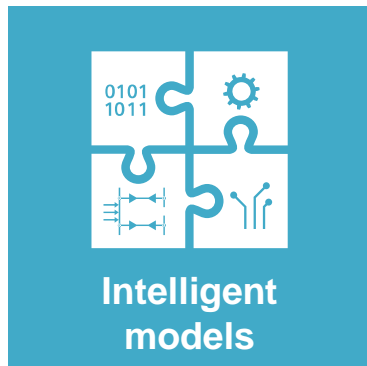
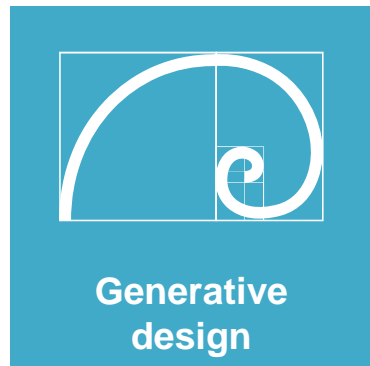
↑ Regulation

Technological Forces Transforming Industry

Changing the way
products come to life

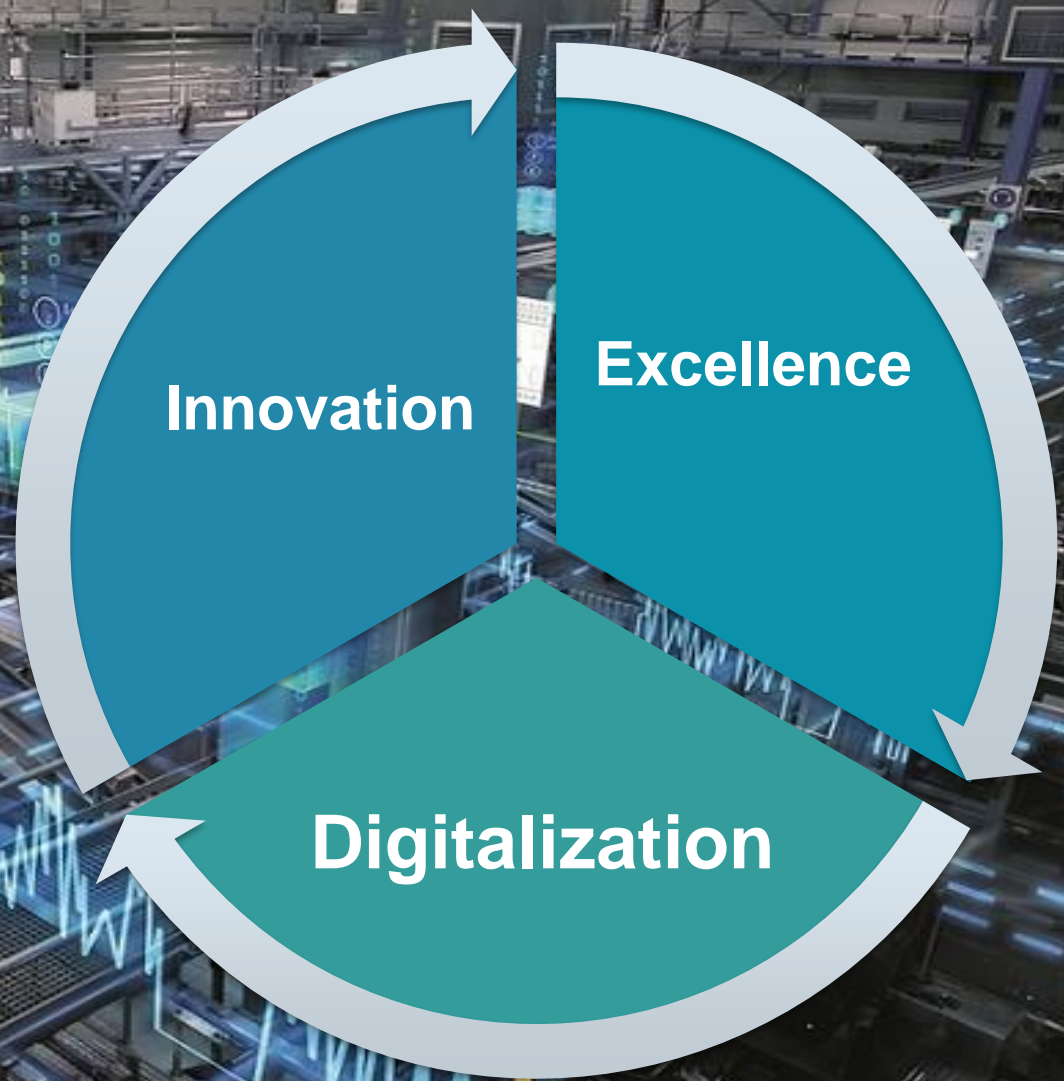
Changing the way
products are realized

Changing the way
products evolve

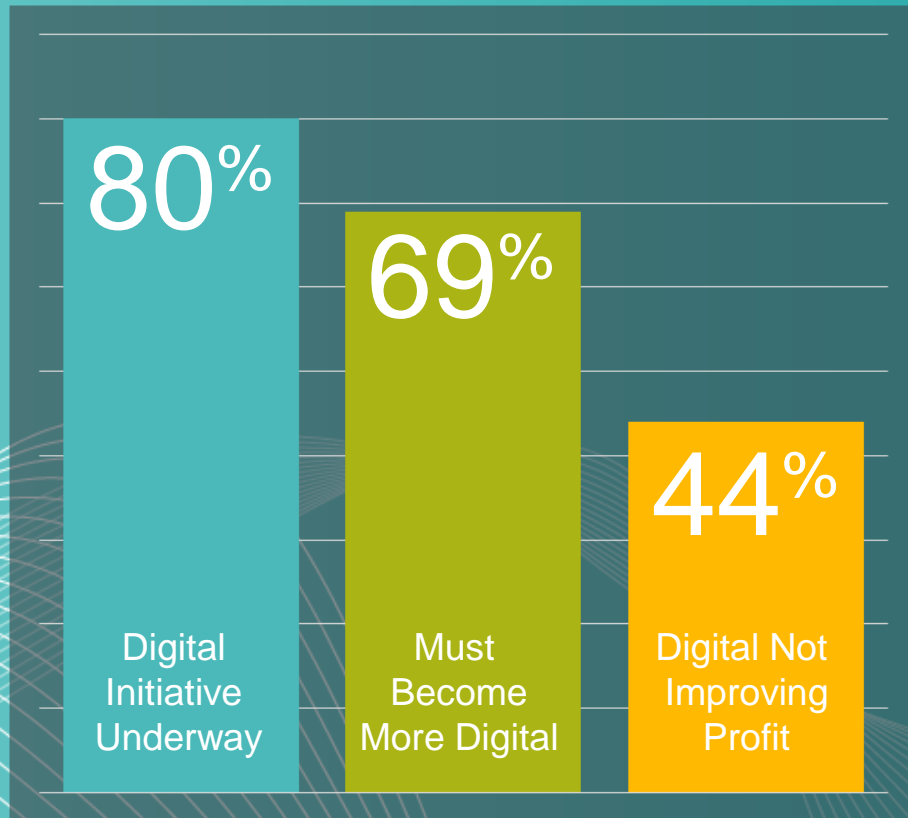


**Trends like
Industry 4.0
Provide a Framework
for Addressing the
Challenges of Modern
Manufacturing.**

**But how do you
implement them?**



SENIOR EXECUTIVE VIEWS ON DIGITALIZATION



“Digitalization success depends less on having the most advanced technologies and more on having the right operating systems.”

CEB GLOBAL, 2017

Digitalization Delivers Value & Excellence



PRODUCT	PROCESS	ASSETS AND MATERIALS	QUALITY
Time to market Quality	Setup time Work instructions	Equipment utilization OEE, ROA, inventory turnover, waste	Online Process Interlocking
Chinese Telecom Factory +25% Units shipped	Japanese Automotive Company +\$1.4M Annual savings	Chinese Telecom Factory +100% Operator efficiency	German OEM Invaluable data for ZERO Defect initiative

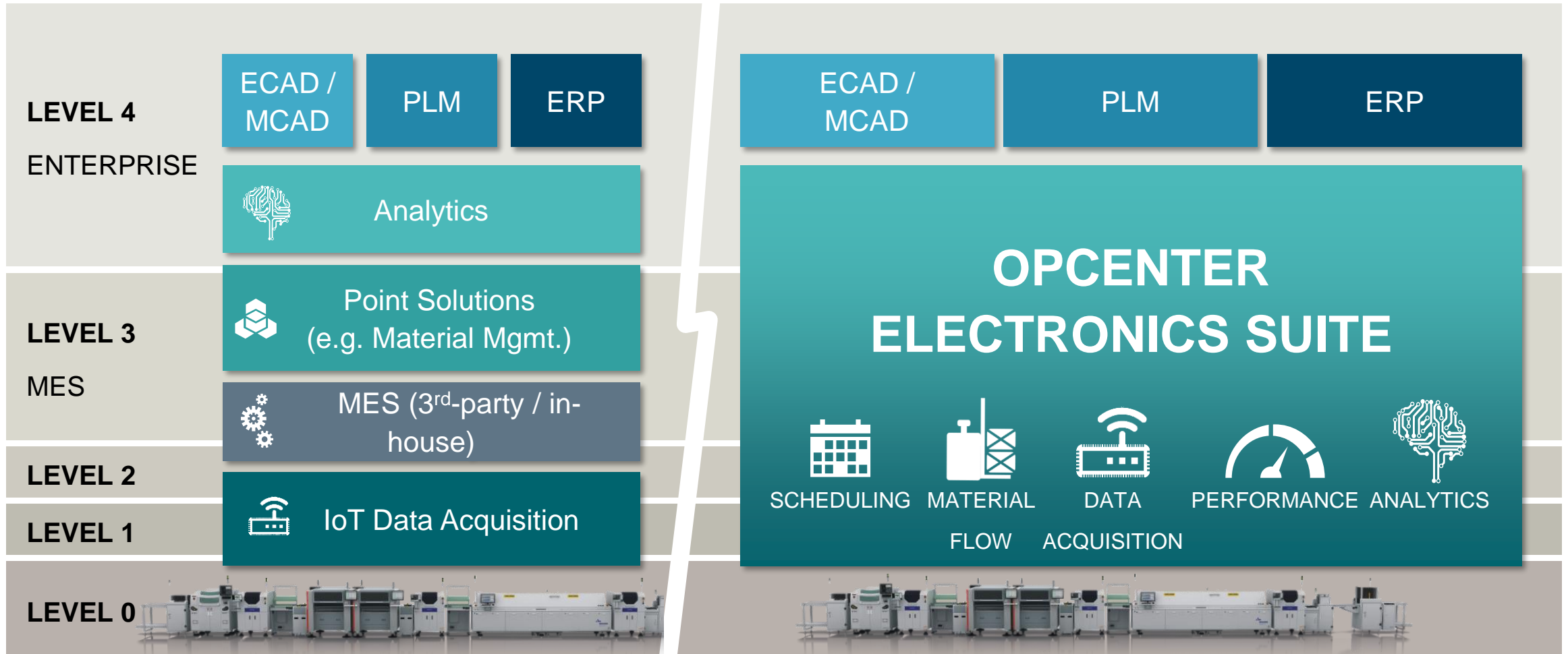
Digitalization Delivers Value & Excellence



PERFORMANCE	PROCESS MONITORING	FINDING BOTTLENECKS	BOXBUILD
Global Decision Making	Changeover Optimization Guided Shop floor Operations	Drill Down to the Details	Manage Guided Assembly & Test
Automotive FTS  80% → 52% OEE → LIVE OEE	Top 50 Global EMS 29k Components ↓ 37k Components ↓ 42k Components ↓ 50k is the max!	Top 50 Global EMS Waiting 60 hours monthly for the reflow oven! 60 Hrs Added another oven instead of another line	European EMS 1,410 DPMO ↓ 568 DPMO Saving/Yr \$170k

Providing both Data solutions and Enterprise MES

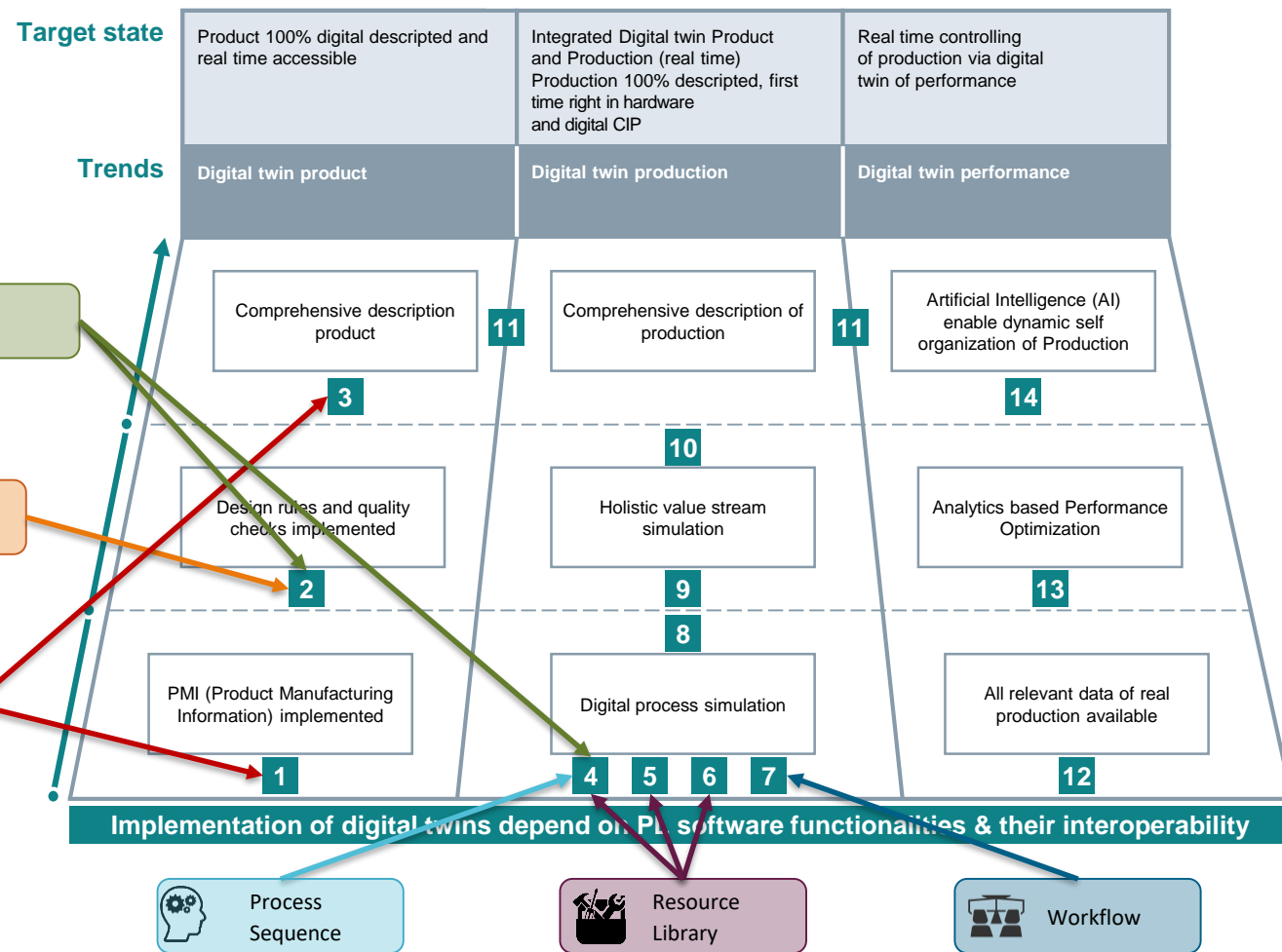
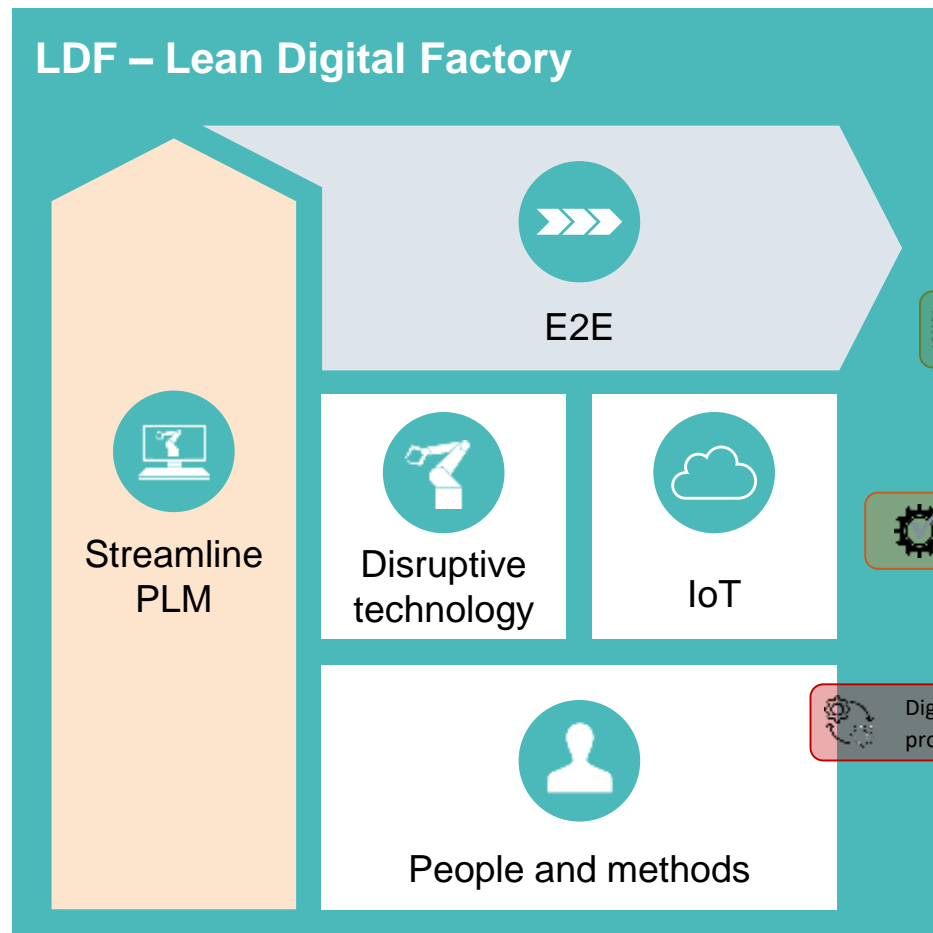
ISA-95





Streamline PLM

Lean Digital Factory (LDF) modules





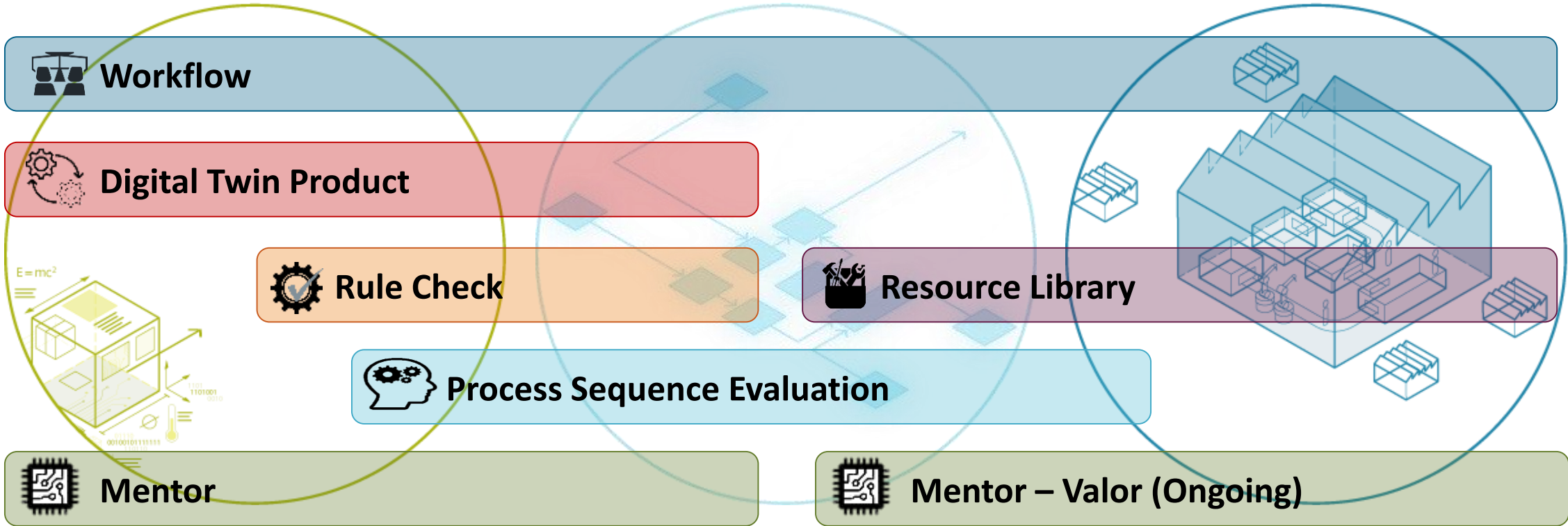
SPLM Mapping of PoCs to Digital Twin Approach



Digital Twin Product

Digital Twin Production

Digital Twin Performance

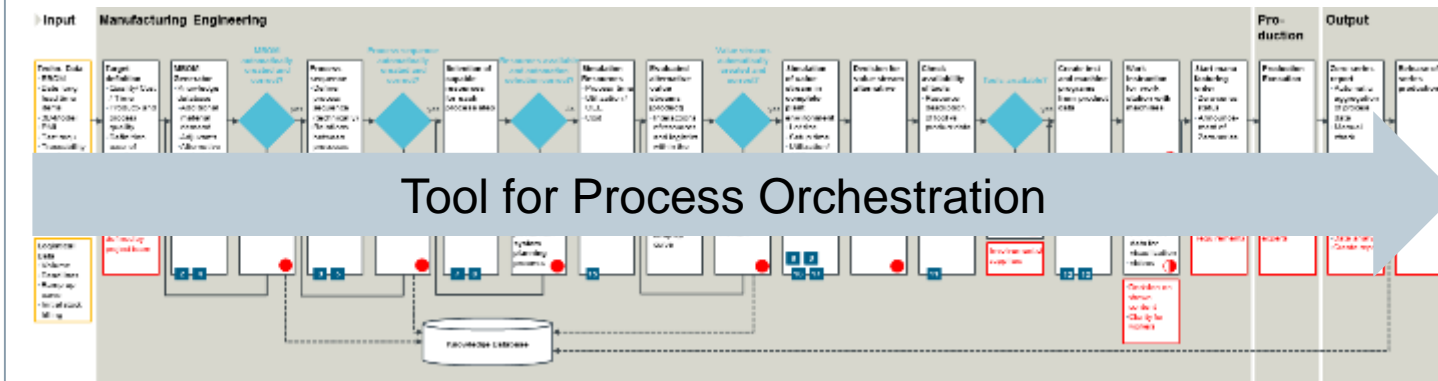




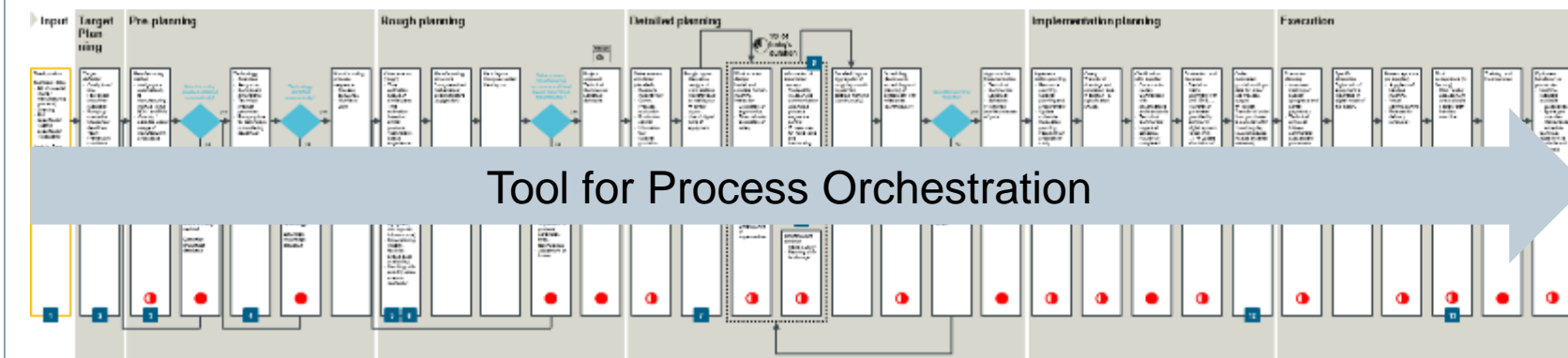
PoC Workflow Engine

Workflow

Ref Process: NPI = New Product Introduction



Ref Process: NMI = New Machine Introduction





Workflow PoC supports the NPI¹⁾/NMI²⁾ reference processes (NPI: 2000/year @ EWA; 600/month @ WKC)

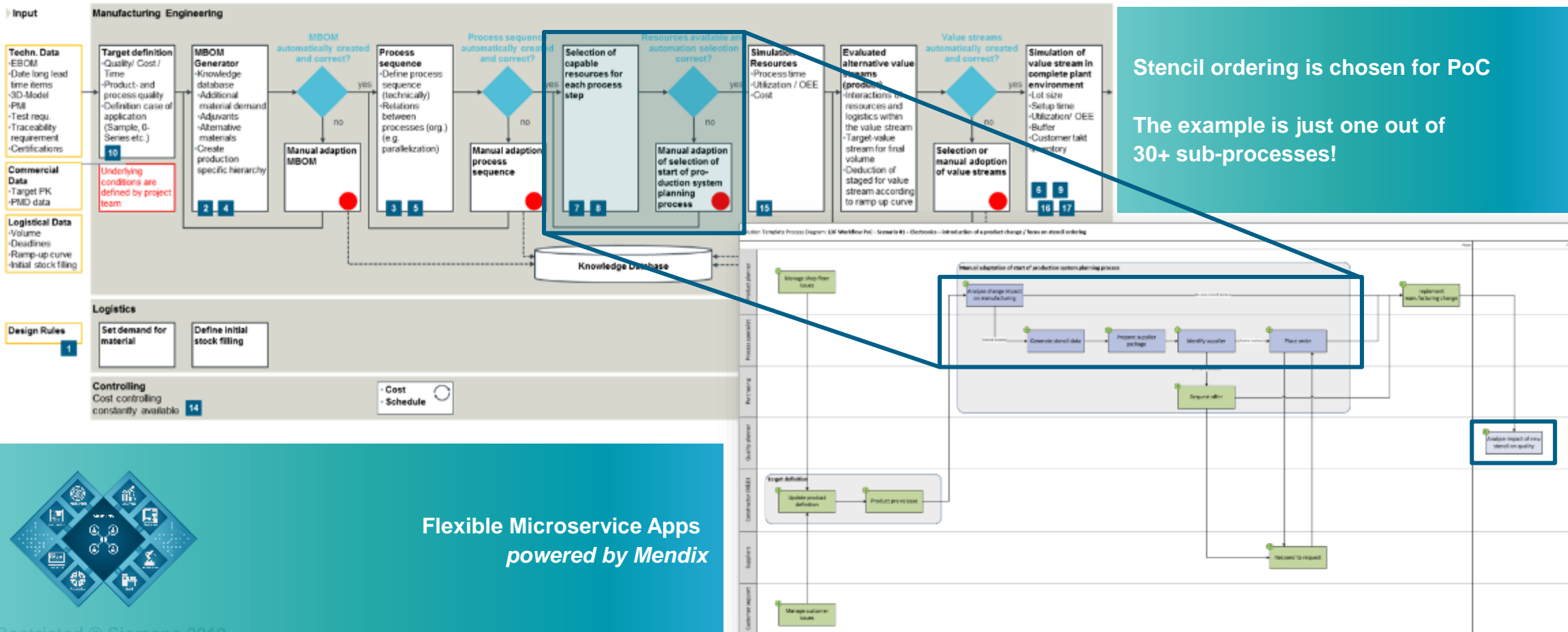


Workflow

Evaluation of a workflow engine

●●● PoC completed	● PoC extension requested
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Detail view: Reference process product introduction – Part 1/2



**Flexible Microservice Apps
powered by Mendix**

Restricted © Siemens 2019



The PoCs digital twin product and DI-wide resource library resulted in a standard definition and thus reusability for DI



Resource Library

Levels of detail fulfilled by digital twin

Level of Detail (LoD)	Description	Workflow (How to)
LoD 01	Basic Info Name and type of an asset classified according to potential use cases (e.g., production, assembly, logistic, ...)	Workflow (How to) ↓
LoD 02	Supporting Pre-Planning phase as well as implementation and executing of SPLM Descr. of essential asset capabilities (PMI), all relevant data for factory planning & execution process	
LoD 03	Basis for 2D-Layout planning and material flow analytics Factory planning, sensible 2D layout incl. all functional areas and relevant operation pages (operating page, material delivery/flow, maintenance access, ...)	
LoD 04	Enabling for realistic rough layout planning Simplified 3D model (boundary view) with enveloping contours and provision in typ. exchange and planning file formats (e.g., JT)	
LoD 05	Supporting workstation or work-cell design and detail layout of the factory 3D model based on NX incl. kinematic axes (if relevant for subsequent use in corresponding planning tools); NX assembly of complex parts (single resources) for integr. into combined plant project planning	
LoD 06	Implementation planning and physical simulation evaluation (if needed) Native 3D design model incl. all material types and surface properties for simulation of physical, electrical and so on properties (e.g., FEM, thermo, ...)	
LoD 07	Execution phase based on specific simulation and virtual commissioning Mechatronic System/Cyber-physical model including all electrical capabilities for virtual commissioning, programming and simulation	
LoD 08	Closed loop with life cycle data from operating phase Aggregated process and event data from MindSphere applications and microservices for reuse in next planning phase or scenario validation/simulation	

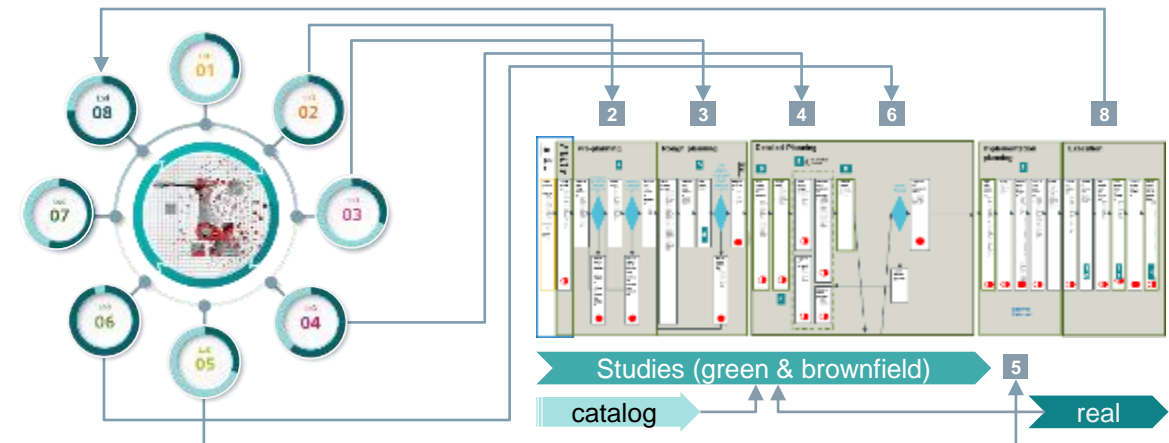


Linked to standard

PI0674 – Introduction of systems

Linked to supplier

Linked to the reference process



Level of Detail (LoD)

Frame Specification for Supplier

IN0692 – SITEMA

Purchase order



Digital twin of product

DF wide production resource library

PoC completed

PoC: Evaluate defined concept

PoC completed

Pilot: Pre-filling of library



Work Based Interaction with Robotics

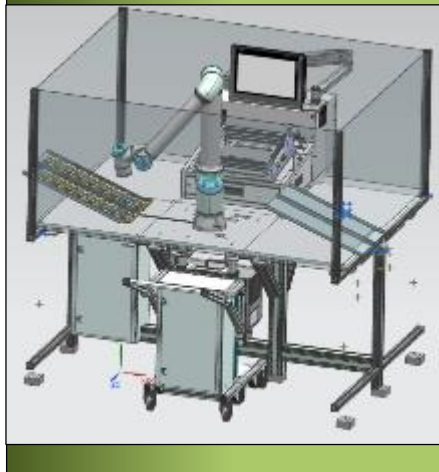
Fraunhofer IWU, Chemnitz ©

Classical/ LWR versus Collaborative



Classical/Light Weight

Collaborative



Standard robot carrier system

- Increase efficiency
- Improve ergonomic
- High flexible
- High tact time
- ROI < 2a



SIMOVE is evaluated as Master Controller for Autonomous Mobile Robots (AMR) and forklifts



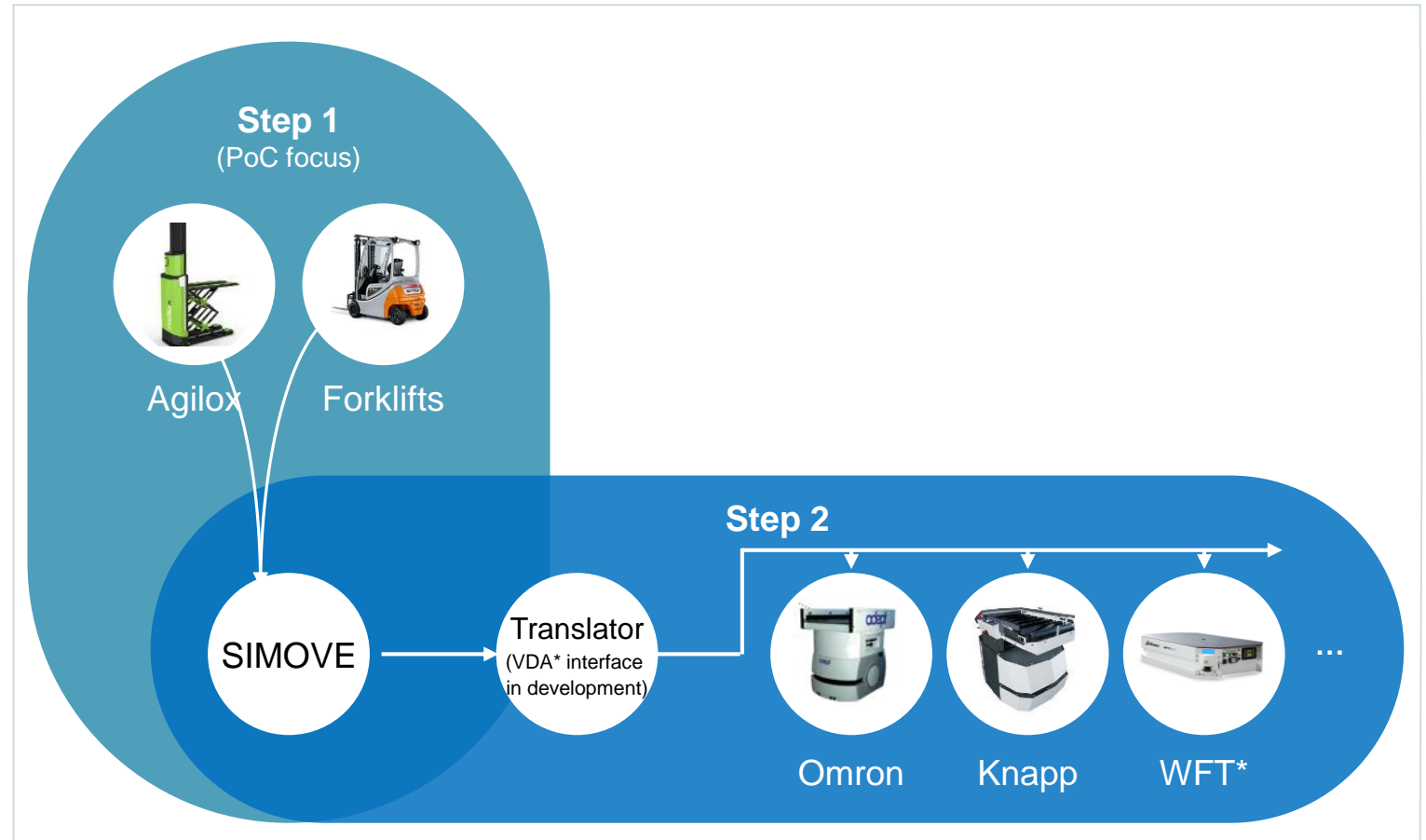
A unified control system for transport order assignment is needed

From separated control systems to one Master controller

Step 1 (PoC Focus): Control forklifts & Agilox with one system

- Transfer forklift control system functionalities to SIMOVE
- Realize interface to Agilox

Step 2 : Control forklifts & different AMR types with one system



Closed-Loop Manufacturing – OpCenter Execution Electronics

The most frequent use cases for CLM

Work instructions and 3D visualization

Improved operator experience to access the right work instructions, 2-D & 3-D models



Design for Manufacturability

Collaborative (BOP) approach between engineering and manufacturing to design a process for manufacturability



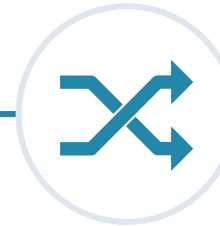
Electronic Work Instructions (EWI) harmonization

Provide necessary tools to author manufacturing work instructions consistent with design requirements



Cross-domain change management

Global change and configuration management



Shop floor issue closed-loop

Ability to take containment actions in the Shop Floor & escalate systemic problems to Engineering for corrective actions



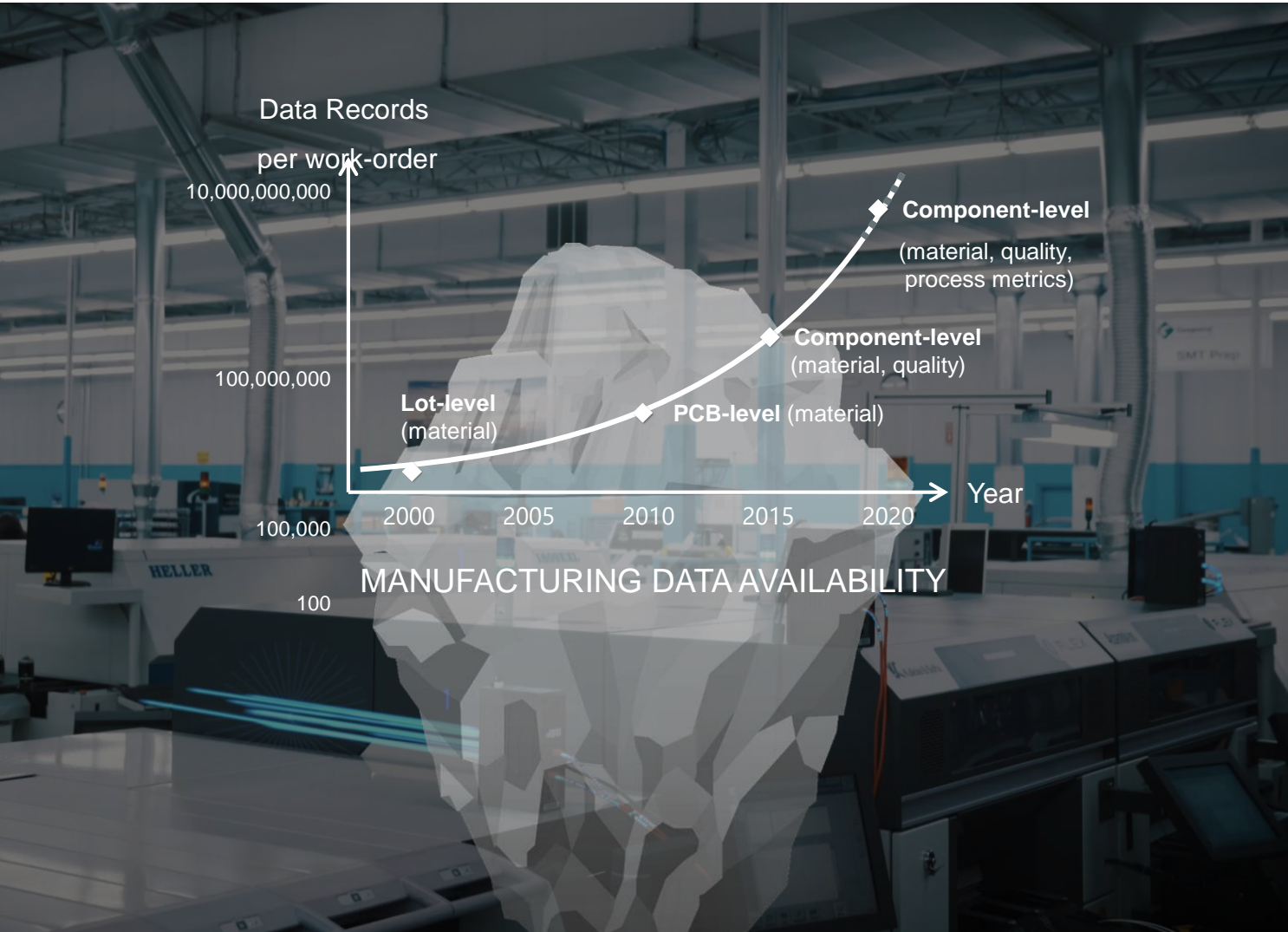
Options & variants

Ability to configure manufacturing process for the product family and dynamically apply the configured process requirements for appropriate orders



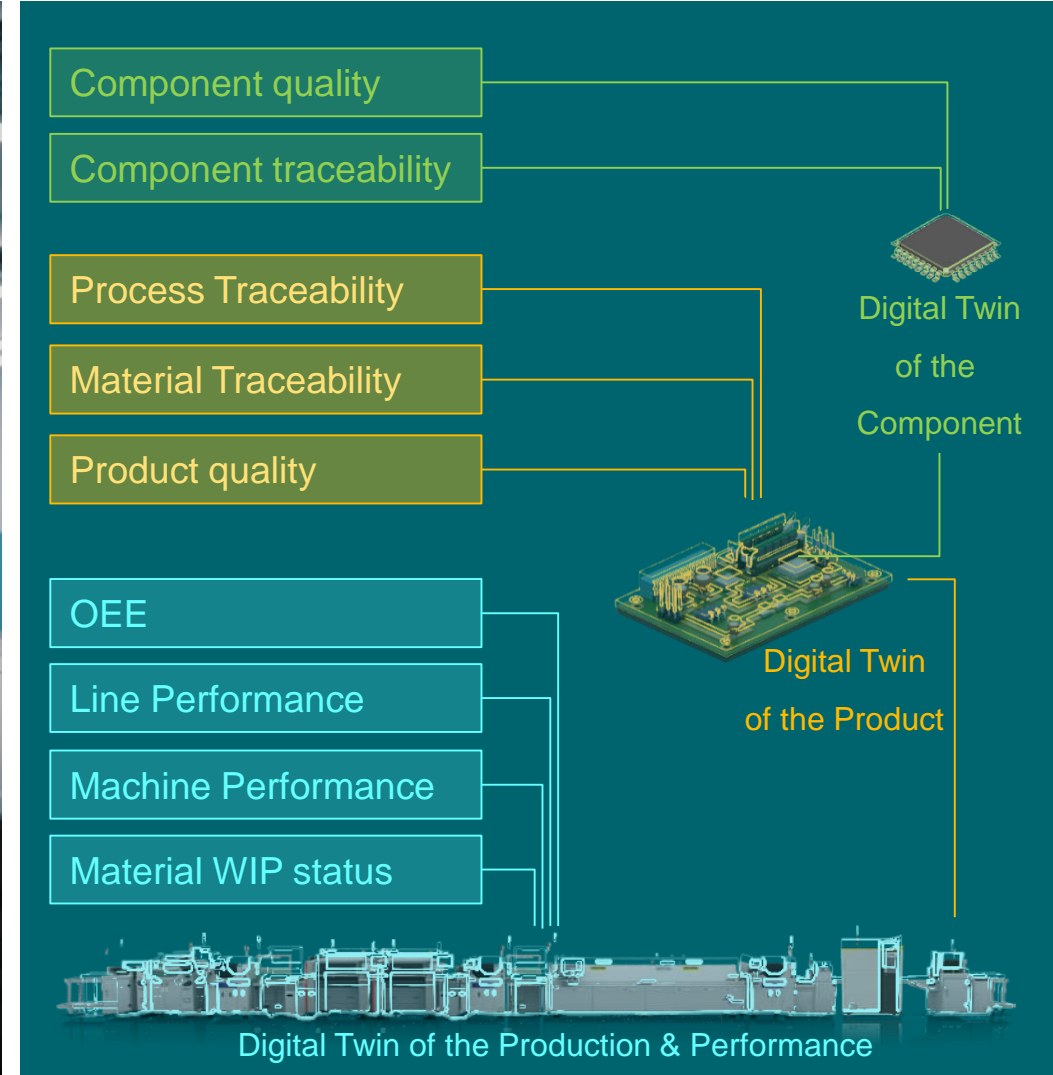
Data Acquisition → Analysis → Insights → Action

SIEMENS
Ingenuity for Life



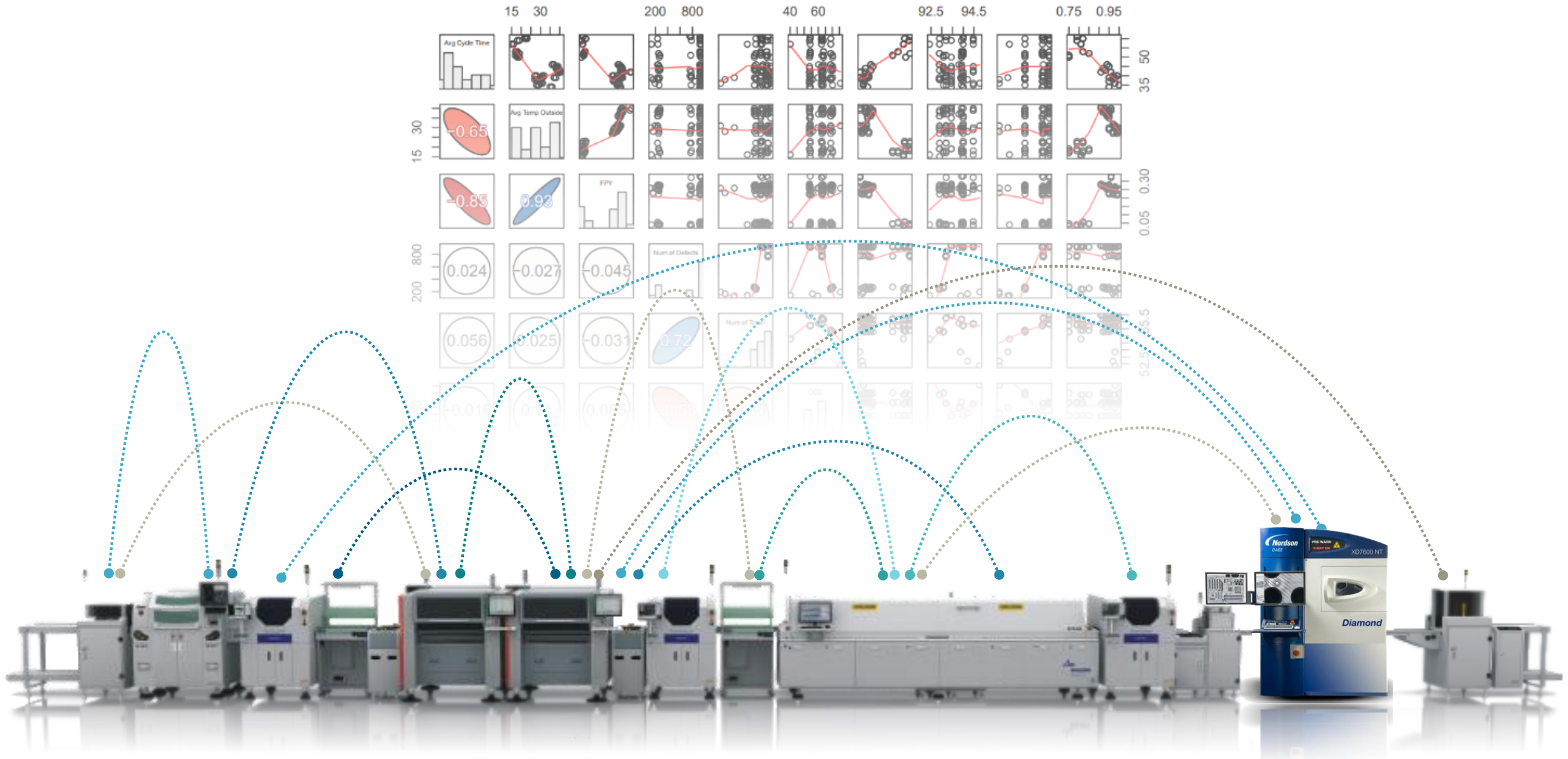
Data Acquisition → Analysis → Insights → Action

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Data Acquisition → Analysis → Insights → Action

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"In the product, the value of the raw material is 80%, but then you have scrap and inventory failure, and that can kill your profit! The material must be under control"

*Franco Oliaro
ROJ CEO*



Challenge

Material Overspend

Inefficient flow of materials and missing real-time visibility of material quantity across the factory leads to inflated inventory spend, material obsolescence, poor production efficiency and waste of shop-floor space



SOLUTION

Aggregate data from manufacturing lines, kitting stations and warehouse, to generate prescriptive model of material flow

RESULTS

€150K – Excess inventory reduction

€2M

20% Reduction in obsolescence

20% Production efficiency increase

1 Data Acquisition

Machine performance

Warehouse inventory

Work-order
Bill of Material

2 Analysis & Insights

Predict material run-out

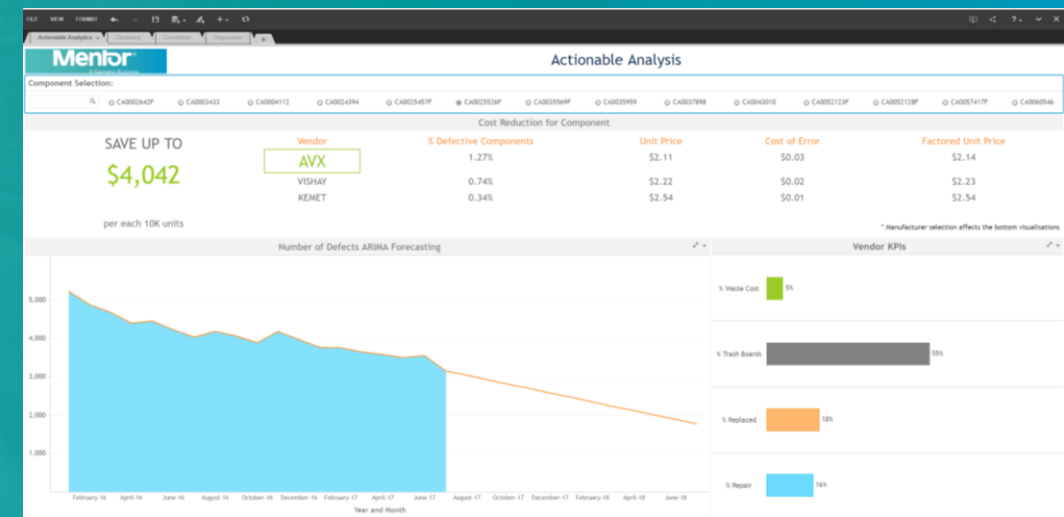
Prioritize material selection

Minimize change-over effort

3 Action

Proactive picklist generation – deliver the right material, at the right time

Change-over instructions (change / keep / remove)



Closed-Loop Feedback from Manufacturing to Design via Manufacturing Execution System (Available Today)

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Collaborative
interaction
among Design,
Engineering and
Execution
domains based
on seamless
integration

The screenshot displays the CAMSTAR Manufacturing Execution System (MES) interface. At the top, the header includes the CAMSTAR logo, navigation menus (Container, Event, Search), and user information (Hello, AndyAssembler). The main workspace shows a task list on the left and a detailed view of the current task on the right.

Task List:

- 01 DriveSetup Components (Passed)
- 02 Install Video Port (Not Executed)
- 03 Install Flash Drive (Not Executed)
- 04 Install Hard Drive Ribbon (Not Executed)
- 05 Install Software (Not Executed)
- 06 Move to Inventory (Not Executed)

Task Details (Task 2 of 6):

- Instructions:** Insert video port and screen into place.
- 3D Model:** A 3D CAD model of a device with an orange video port being inserted into a slot. A callout indicates "Install two screws".
- Workstation:** A dropdown menu for selecting the workstation.
- Left Gap:** A numeric input field set to 1.5 mm.
- Right Gap:** A numeric input field set to 1.5 mm.
- Buttons:** "Reset" and "Execute" buttons.

System Status: SUCCESS! Components issued at Step Drive Setup on 20.04.2017 04:06:36 by Operator.

Machine-to-Machine Closed-Loop Feedback (POC)



Automatically trigger equipment maintenance based on real-time quality metrics

The screenshot displays a Siemens software interface for a factory simulation. On the left, a 'Form1' window shows a traffic light indicator with 'STOP' (red), 'CLEAN' (yellow), and 'PASS' (green) lights, with 'PASS' selected. Below it, an 'SPI CHECK' window shows 'SPI Status' as 2314, 'PIN PASS' as 1016189, and 'PIN FAIL' as 523. It also displays counts: 'STOP COUNT' (32), 'FAIL COUNT' (0), and 'CLEAN COUNT' (0). At the bottom of this window are buttons for '- STOP -', '- CLEAN -', and '- START -'. The main interface shows a 'Factory - Valor MSS Workspace (Admin)' window with a 'Factory Layout' view and a table of factory components. A 'USI-SPI-FileParser' dialog box is open, showing input and output paths and a timer of 2000. A file explorer window shows the contents of a 'spifiles' folder, including 'error', 'samplertest', and 'success' files. A large Chinese text overlay at the bottom reads '開始採集數據並統計' (Start collecting data and statistics). The system tray shows the date and time as 12:51 PM on 10/19/2017.

Display Name	Box	Status
SMT B		
SMT C		
SMT D		
Demo Line		
Test Line		
Repair 1		
SMT IoT		
10043 - SP60		
10045 - SPI		
10045 - Samsung		
10047 - Reflow Oven		
10048 - AOI		
ICT Testing		
ICT 1		
ICT 2		
MI and Final Assembly		
MA 1		
MA 2		
System Assembly 1		
System Assembly 2		
Repair 2		
Final Testing		
Functional Testing		
Environmental Testing		
Final Repair		
Packing and Shipping		
PC Card Packing		
PC Cards Stock		
System Product Packing		
System Products Stock		
Dispatch		
SN Registration		
SN Registration		
WIP		
WIP		
Default		
Default		
Default		

Use Case Vacuum Gripper





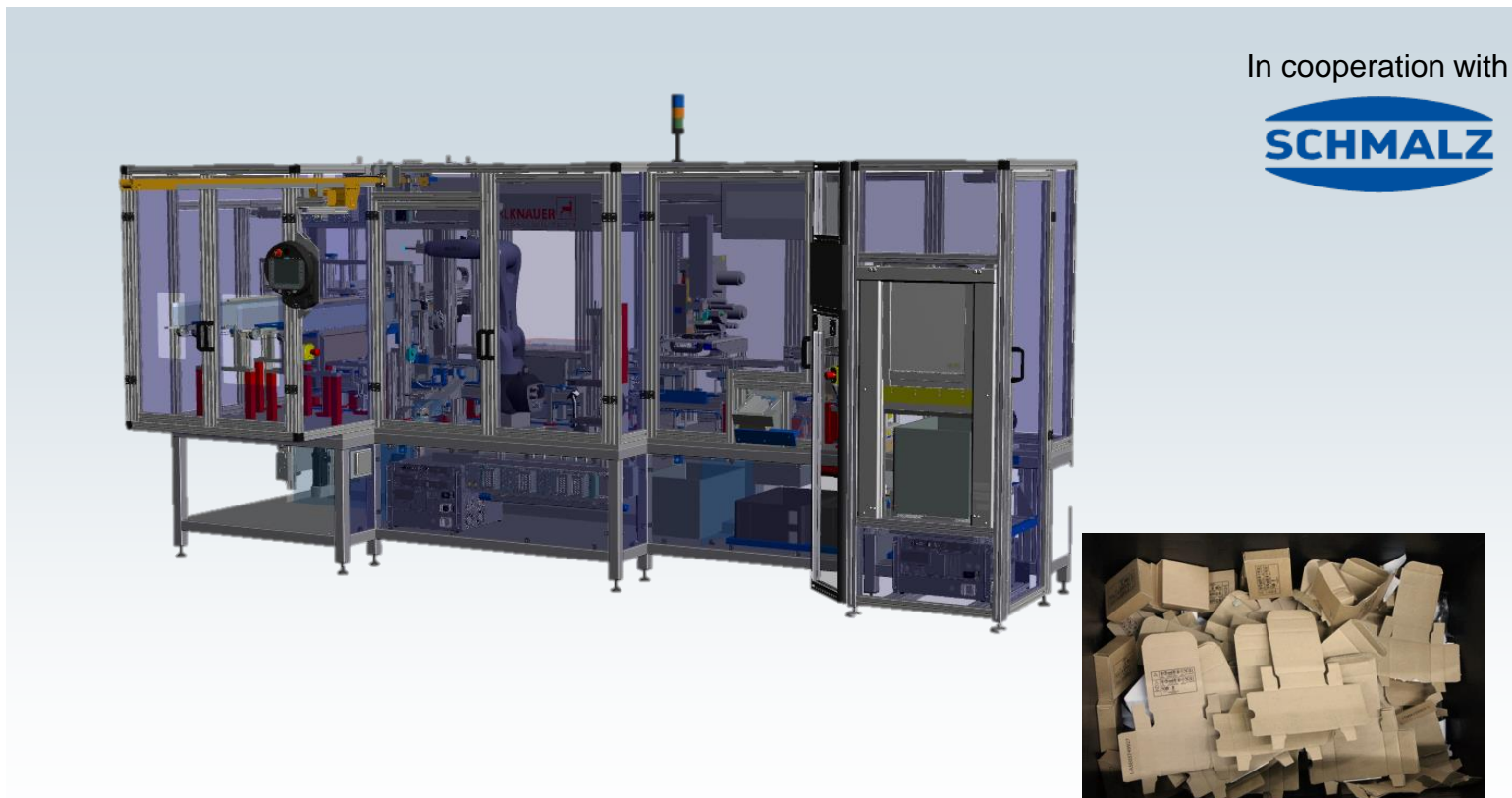
Stabilization of packing machine by online monitoring of vacuum grippers

SIEMENS
Ingenuity for Life

Challenge

Regular contamination of vacuum system due to heavy dust

Aggregation of process data without re-programming the PLC or intervention in the running process



In cooperation with





Splitting real time data for PLC and maintenance information for IT

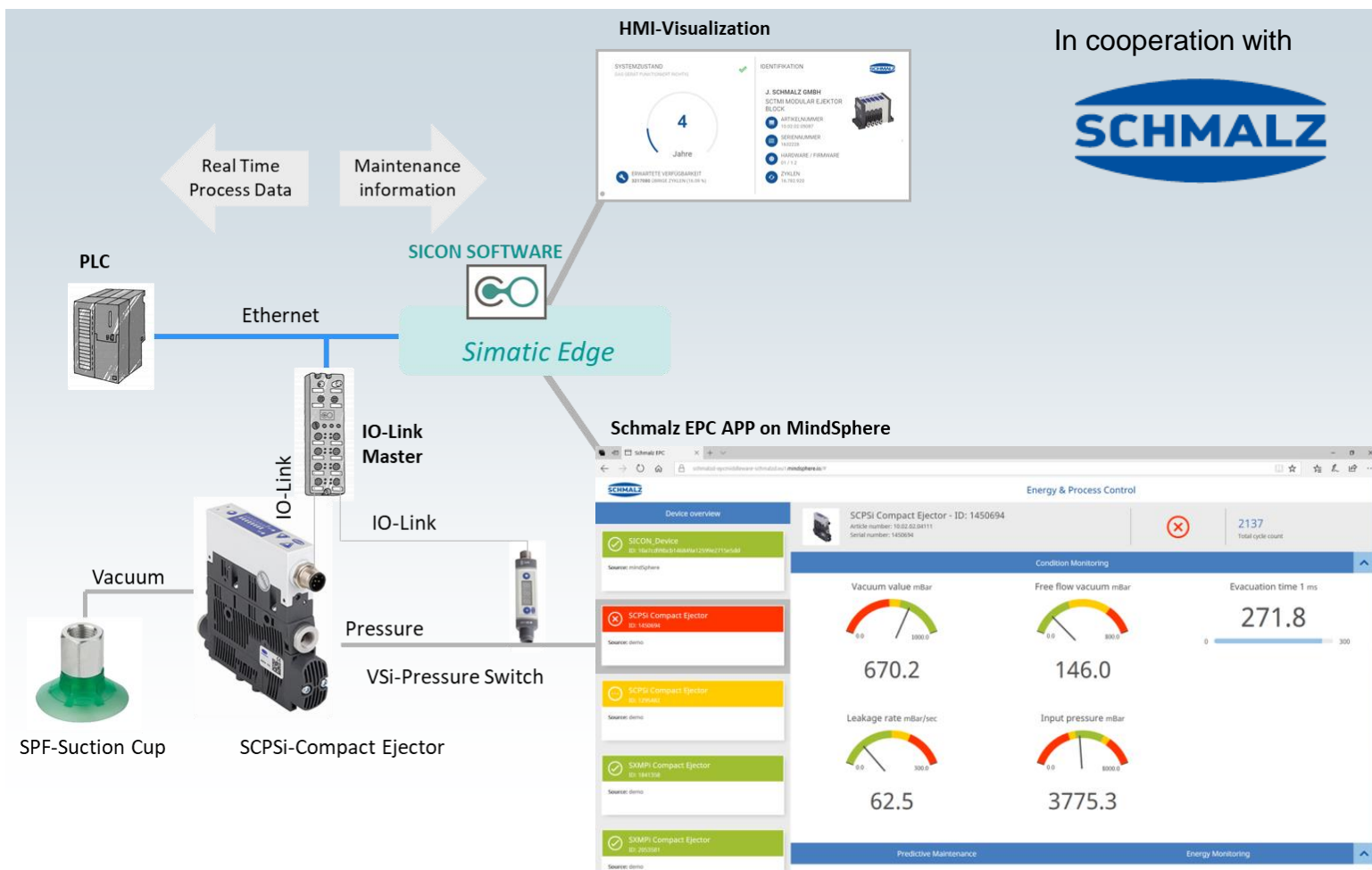
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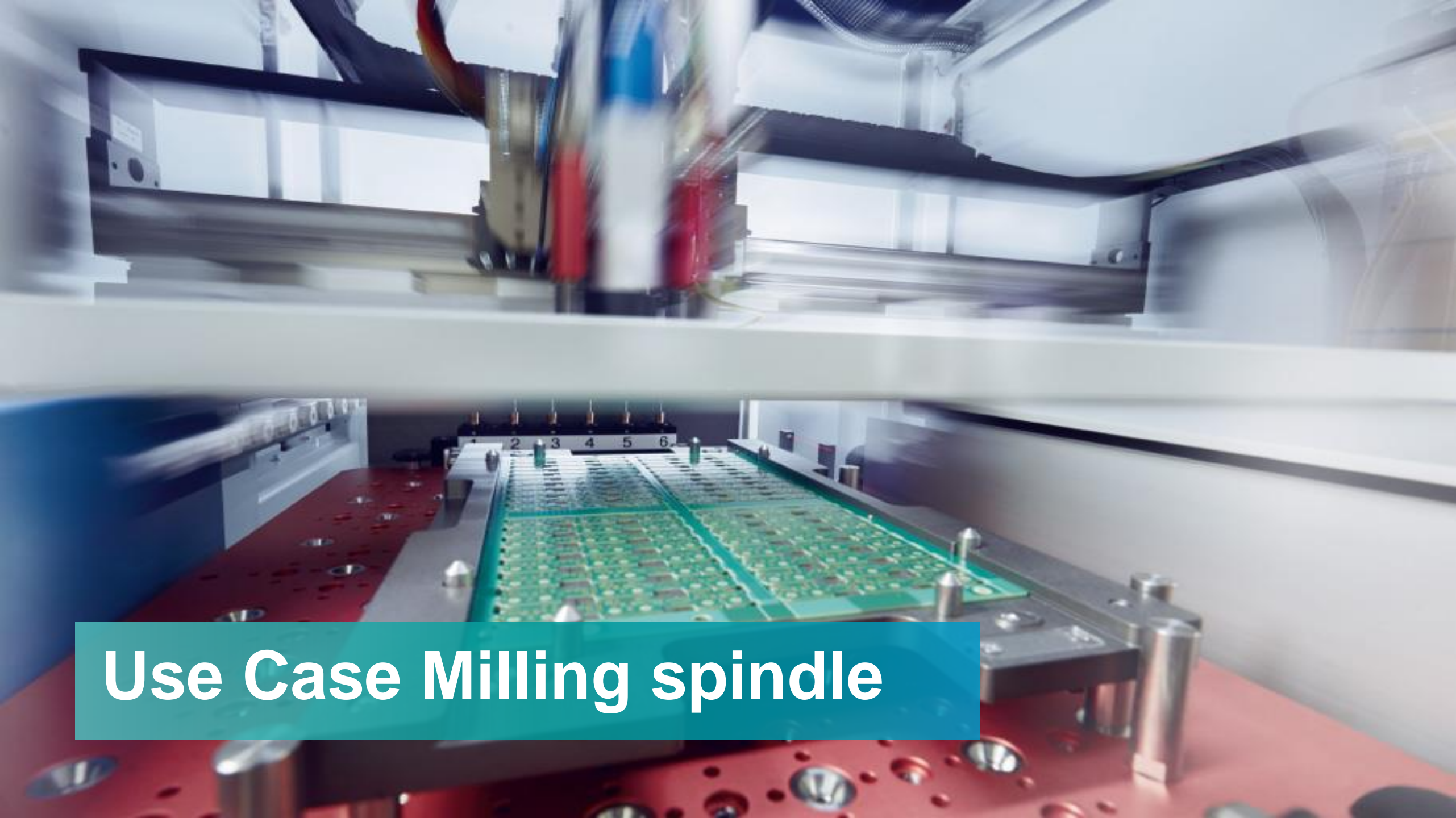
Solution

Easy integration of a Schmalz-specific condition monitoring in machine HMI and notification when to clean the filter

Utilization of the Schmalz EPC App with additional services

Scalable Plug&Play Connectivity

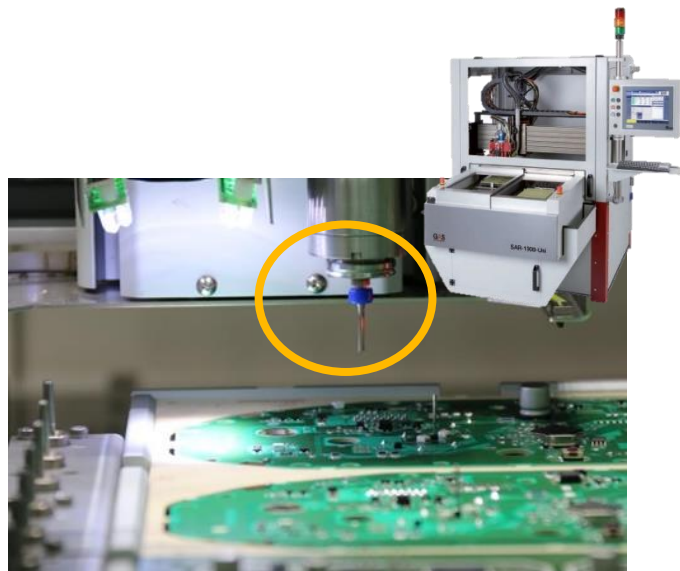




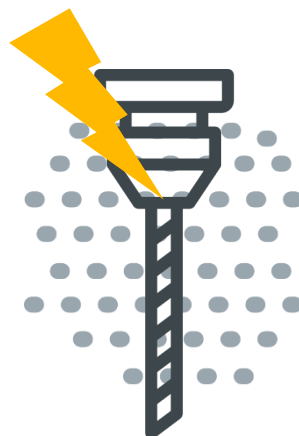
Use Case Milling spindle



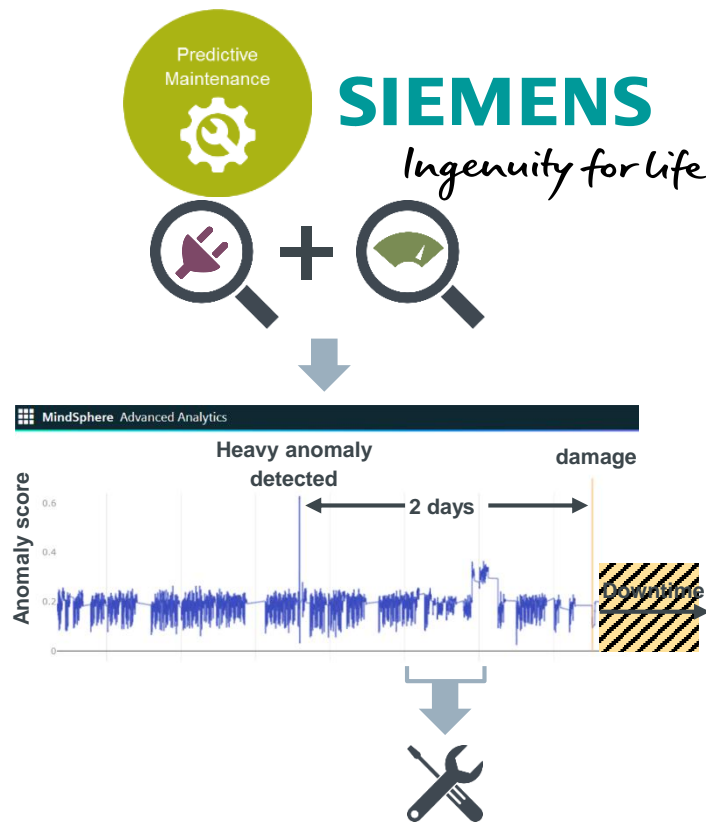
Predictive Maintenance for depaneling machines



Objective:
Milling spindle in a printed circuit board depaneling machine



Problem:
Aggressive milling dust causes stiffness, which leads to machine failure



Target and approach:
Detect critical condition via current- and rpm analysis
✓ Edge app predicts downtime
✓ Cloud for alert & dashboard

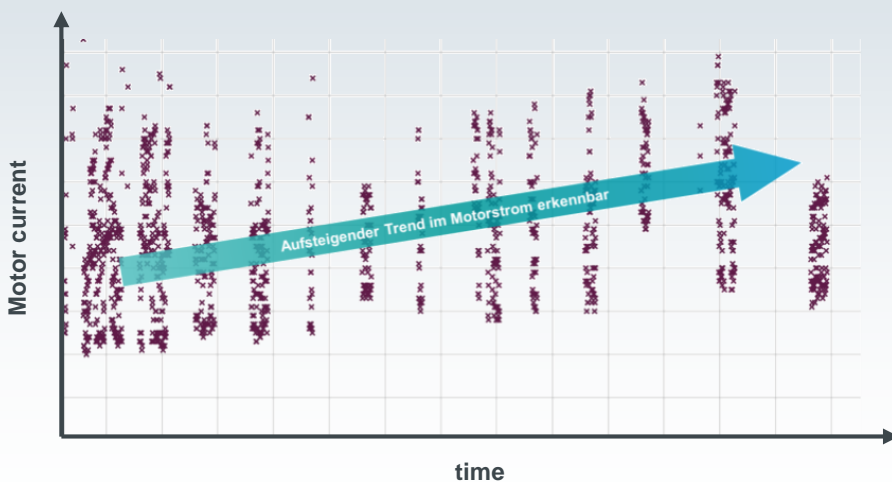


Best results by combining different analytic methods



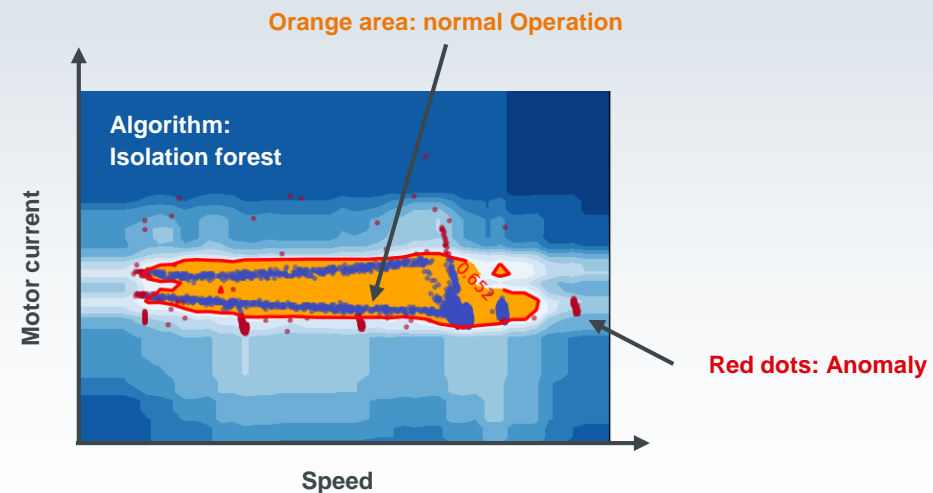
Trend analysis

Target: Locate downtime period



Anomaly detection

Target: Set trigger for service routine



The algorithm detects downtimes up to 2 days in advance!



SIEMENS AMBERG

CHALLENGE

Using X-Ray test on every PCB is slow, expensive and reduces overall line performance

Solder paste

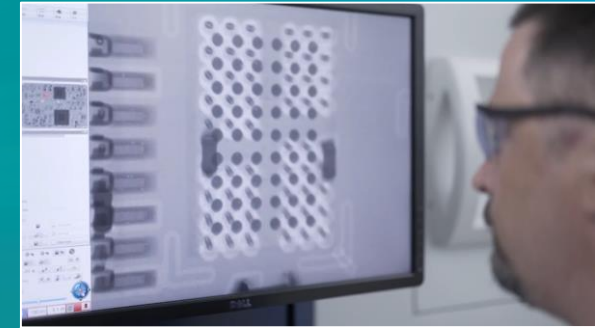
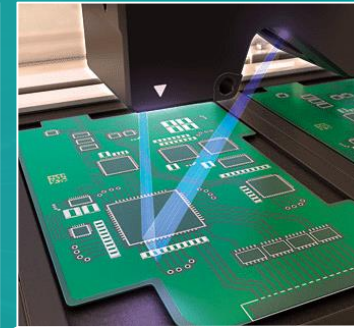
Root-cause for 60% of PCB Assembly issues

Solder Paste Inspection

collects data about the applied solder paste

X-Ray Inspection

- Checks quality of solder joints after soldering
- Slow and expensive
- Potential process bottleneck



SOLUTION

Use solder paste inspection data to predict the need for X-Ray inspection of each PCB

RESULTS

30% Reduced x-ray testing volume

10% Improved line utilization

1



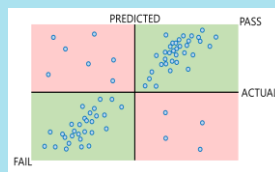
Collect solder paste and X-Ray inspection measurements and pass / fail data

2



Supervised machine learning algorithms – Determine which PCB can skip X-Ray inspection

3



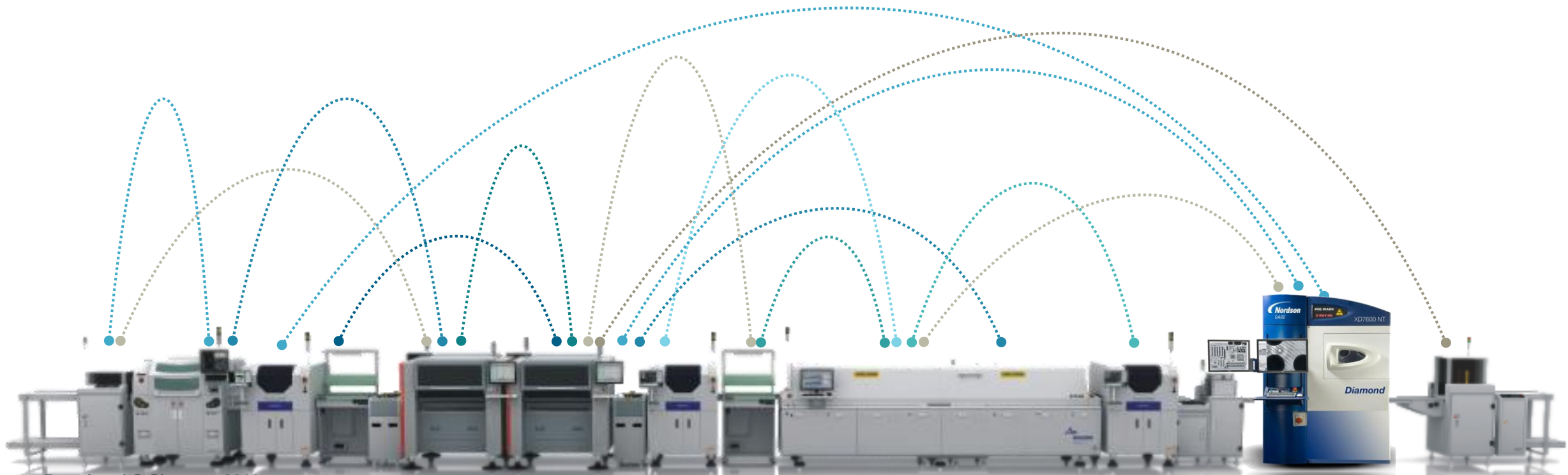
Continuously re-train the machine model to increase prediction accuracy



Data Acquisition → Analysis → Insights → Call to Action



What is your vision?
We can do it together



Thanks; Tack

Frank Bleisteiner
DI FA MFG

Sagi Reuven
Valor BD

Twitter: #beitgugb

www.siemens.com